Message from the TPC Chairs
HOTI 2020

Welcome to the 2020 IEEE 27th Annual Symposium on High-Performance Interconnects. This conference brings together designers and architects of high-performance networks, with presentations from universities and industrial research laboratories that focus on the latest developments in leading-edge technologies. This year's conference is entirely virtual due to the COVID-19 pandemic, representing unique challenges and opportunities for the conference program.

Our world-class team of 19 Technical Program Committee members returned insightful reviews for 29 submissions. Each paper received between three and four reviews, thus providing ample and valuable feedback to the authors, and ensuring high confidence on the outcome of the review process. Out of the 29 submissions, 10 were accepted.

The technical program comprises five technical sessions that cover a number of hot topics in high-performance interconnection networks. The paper sessions open with hardware related papers, and are followed by a session on frameworks and architectures. Our second day has three sessions: one session is dedicated to advances in machine learning for networks; a second session centers on topologies and routing; and our last session concentrates on containers and virtualization. In addition to the technical papers sessions we have two distinguished keynote speakers, Michael Kagan (NVIDIA) and Brian Barrett (AWS EC2), in addition to two invited talks on cutting-edge network design.

The organization of a major conference such as Hot Interconnects is a demanding and time-consuming task. We would like to thank the TPC members for their thorough reviews and active participation, despite the traditionally short review cycle of Hot Interconnects (less than one month). Owing to their dedication and promptness, Hot Interconnects is able to bring you high-quality, up-to-the-minute contributions.

We especially thank General Chairs Don Draper and Khaled Hamidouche for their leadership and guidance and for their enormous contributions in organizing this meeting. In addition, we would like to express our gratitude to the members of the Organizing Committee for their contributions.

Finally, and most importantly, we thank the technical paper authors, keynote and tutorial presenters, and panelists for their excellent contributions that make this event the premier international conference for high-performance interconnects.

We hope you will enjoy the symposium!

Ryan Grant, *Sandia National Laboratories*
Manjunath Gorentla Venkata, *NVIDIA*
HOTI 2020 Technical Program Co-Chairs